

PATENT ASSIGNMENT

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SUBMISSION TYPE: NEW ASSIGNMENT

NATURE OF CONVEYANCE: ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Hsueh An YANG	06/13/2007
Meng Jen WANG	06/13/2007
Wei Chung WANG	06/13/2007
Ming Chiang LEE	06/13/2007
Wei Pin HUANG	06/13/2007
Feng Chen CHENG	06/13/2007

RECEIVING PARTY DATA

Name:	ADVANCED SEMICONDUCTOR ENGINEERING, INC.
Street Address:	No. 68, Heping Rd.,
Internal Address:	Pingtung County
City:	Pingtung City
State/Country:	TAIWAN
Postal Code:	900

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12126043

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: 4459-274

PATENT

500547941

REEL: 020990 FRAME: 0107

OP \$40.00 12126043

NAME OF SUBMITTER:

Melissa Satorre

Total Attachments: 3

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ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) _____	Hsueh An YANG	(4) _____	Ming Chiang Lee
(2) _____	Meng Jen WANG	(5) _____	Wei Pin Huang
(3) _____	Wei Chung WANG	(6) _____	Feng Chen Cheng

who have made a certain new and useful invention, hereby sell, assign and transfer unto

Advanced Semiconductor Engineering, Inc.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

MICRO-ELECTRO-MECHANICAL-SYSTEM PACKAGE AND METHOD FOR MANUFACTURING THE SAME

for which an application for United States Letters Patent was filed on _____, and identified by United States Serial No. _____; or

(a) for which an application for United States Letters Patent was executed on June 13, 2007,

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside our signatures:

INVENTORS**DATE SIGNED**

1) Signature: <u>Hsueh-An Yang</u>	<u>June 13, 2007</u>
Name: Hsueh An YANG	
2) Signature: <u>Meng-Jen Wang</u>	<u>June 13, 2007</u>
Name: Meng Jen WANG	
3) Signature: <u>Wei-Chung Wang</u>	<u>June 13, 2007</u>
Name: Wei Chung WANG	
4) Signature: _____	<u>June 13, 2007</u>
Name: Ming Chiang Lee	
5) Signature: _____	<u>June 13, 2007</u>
Name: Wei Pin Huang	
6) Signature: _____	<u>June 13, 2007</u>
Name: Feng Chen Cheng	

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2) Signature: _____ Name: Meng Jen WANG	<u>June 13, 2007</u>
3) Signature: _____ Name: Wei Chung WANG	<u>June 13, 2007</u>
4) Signature: <u>Ming Chiang Lee</u> Name: Ming Chiang Lee	<u>June 13, 2007</u>
5) Signature: _____ Name: Wei Pin Huang	<u>June 13, 2007</u>
6) Signature: _____ Name: Feng Chen Cheng	<u>June 13, 2007</u>

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5) Signature: <u>Wei Pin Huang</u>	June 13, 2007
Name: Wei Pin Huang	
6) Signature: <u>Feng chen cheng</u>	June 13, 2007
Name: Feng Chen Cheng	

PATENT**RECORDED: 05/23/2008****REEL: 020990 FRAME: 0111**